

INTERNATIONAL ELECTROTECHNICAL COMMISSION

IEC 61191-2
Edition 3.0 2017-05

PRINTED BOARD ASSEMBLIES –
Part 2: Sectional specification –
Requirements for surface mount soldered assemblies

C O R R I G E N D U M 1

Figure 5 – J lead joint

Replace, in the table, footnote f by footnote d, and delete footnote e.

iteh Standards
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[IEC 61191-2:2017/COR1:2019](https://standards.iteh.ai/catalog/standards/iec/04e31ba7-9372-4a05-9374-fdf3e1d6bb60/iec-61191-2-2017-cor1-2019)

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